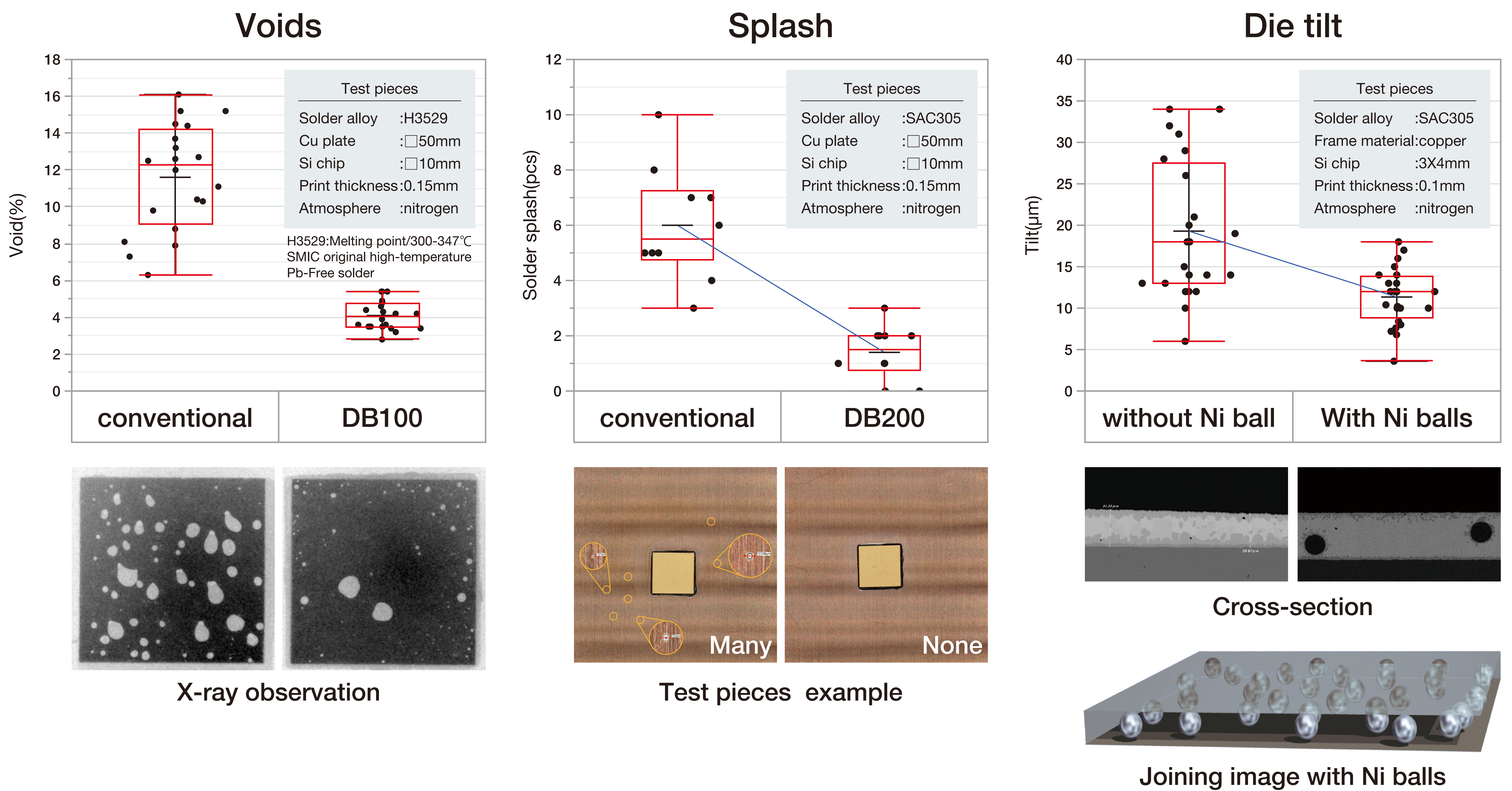
Solder Paste for die-bonding

Solder paste for die-bonding suitable for large area joining

Features

- Achieves reduction of voids in large area joints
- Reduces splash and secure good wire bonding
- It is also possible to reduce the die tilt by adding Ni balls
- Lineup of high-temperature Pb-Free and leaded solder compatible products

Data



Lineup

Item	DB100 Series	DB200 Series	Note
Solder composition	High temperature Pb-Free Lead-based	SAC,Sn-Sb	Please contact us for details
Peak temperature	300-370°C	230-260°C	Adjusted by solder composition
Void	◎Excellent	○Good	During nitrogen atmosphere reflow
Splash	○Good	◎Excellent	During vacuum reflow
Halogen	No addition	No addition	
Cleaning	◎Excellent	◎Excellent	Glycol type,Hydrocarbon type,Semi water type
Process	printing,dispenser	printing,dispenser	
Ni ball contained	Yes	Yes	Please contact us for details

3D-PEIM2021-1E